

# UNHZ203

## Circuit Protector Elements

For overcurrent protection

### ■ Features

- Sharp cutoff characteristics and low voltage drop
- Flame retardant package and low heat generation, high density mounting is possible.

### ■ Absolute Maximum Ratings $T_a = 25^\circ\text{C}$

Parameter	Symbol	Rating	Unit
Operating ambient temperature	$T_{opr}$	-55 to +125	$^\circ\text{C}$
Storage temperature	$T_{stg}$	-55 to +125	$^\circ\text{C}$

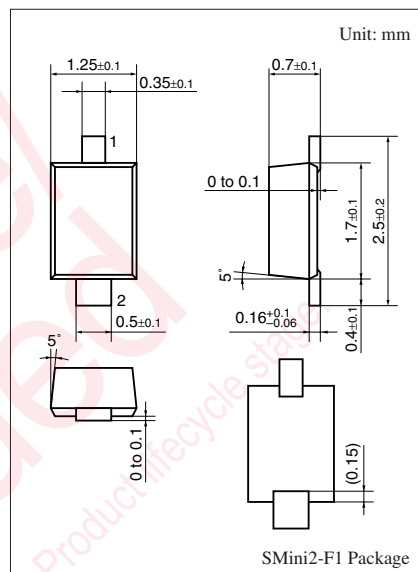
### ■ Electrical Characteristics $T_a = 25^\circ\text{C} \pm 3^\circ\text{C}$

Parameter	Min	Typ	Max	Unit
Rated voltage		50		V
Rated current		1.2		A
Internal Resistance	35	46	57	$\text{m}\Omega$
Cutoff current *		2.4		A

Note) \*: Measurement condition of cutoff current shall be at  $T_a = 25^\circ\text{C}$ ,  $t = 1$  s  
Tolerance of cutoff current shall be  $\pm 20\%$

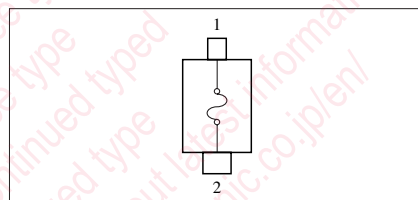
### ■ Usage Notes

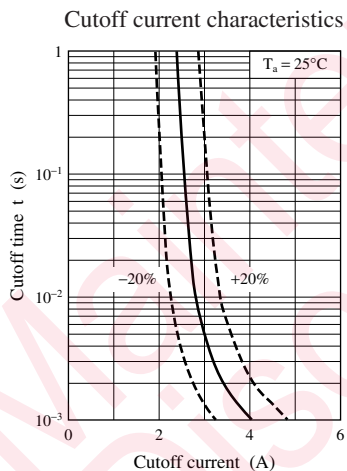
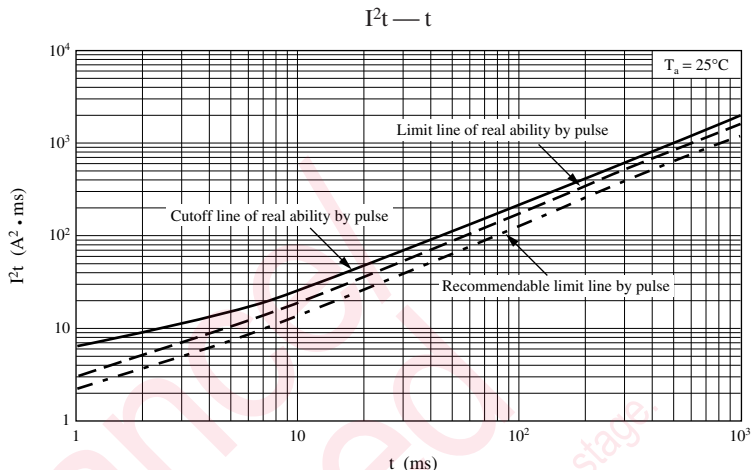
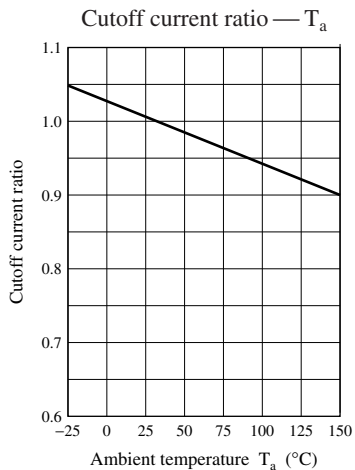
- Package shall be overheated and dangerous for overcurrent.
- This device should be used only to the secondary circuit.  
Package will be damaged for added overpower.
- This device is not electrical fuse legally. Please draw a clear line between electrical fuse from this device.



Marking Symbol: H3

Lead Connection





Maintenance/Discontinued includes following four Product lifecycle stage  
 planned maintenance type  
 maintenance type  
 planned discontinued type  
 discontinued type  
 Please visit following URL about latest information.  
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